

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 61-100. The claims are as follows:

Listing of Claims:

1. (Original) A leadframe adapted to prevent mold compound flash debris, comprising:

a pair of leadframe rails extending along opposite sides of the leadframe; and
a respective mold compound adherence area formed on each of the leadframe rails, the mold compound adherence area having properties that cause a mold compound to adhere to the mold compound adherence area to a significantly different degree than portions of the leadframe outside the mold compound adherence area.

2. (Original) The leadframe of claim 1 wherein the mold compound adherence areas comprise areas having properties that cause the mold compound to adhere to the mold compound adherence area more securely than portions of the leadframe outside the mold compound adherence area.

3. (Original) The leadframe of claim 1 wherein the mold compound adherence areas comprise areas having properties that cause the mold compound to adhere to the mold compound adherence area less securely than portions of the leadframe outside the mold compound adherence area.

4. (Original) The leadframe of claim 1 wherein the mold compound adherence areas are formed on opposite surfaces of the respective leadframe rails.

5. (Original) The leadframe of claim 1 wherein each of the mold compound adherence areas comprises at least one aperture formed in a respective one of the leadframe rails.

6. (Original) The leadframe of claim 5 wherein each of the mold compound adherence areas comprises a plurality of apertures formed in a respective one of the leadframe rails.

7. (Original) The leadframe of claim 5 wherein each of the apertures comprises an aperture having an elongated shape.

8. (Original) The leadframe of claim 1 wherein each of the mold compound adherence areas comprises an area of surface treatment formed on a respective one of the leadframe rails.

9. (Original) The leadframe of claim 8 wherein each of the areas of surface treatment comprises an area of surface roughness formed on a respective one of the leadframe rails.

10. (Original) The leadframe of claim 9 wherein each of the areas of surface roughness comprises a mechanically formed area of roughness.

11. (Original) The leadframe of claim 9 wherein each of the areas of surface roughness comprises a chemically formed area of roughness.

12. (Original) The leadframe of claim 8 wherein the area of surface treatment comprises an area of a material on each of the leadframe rails that is different from a material used to form another portion of the leadframe.

13. (Original) The leadframe of claim 12 wherein the area of material on each of the leadframe rails comprises a panel of the material that is bonded to the leadframe rail.

14. (Original) The leadframe of claim 12 wherein the area of material on the each of leadframe rails comprises a panel of the material that extends through the respective leadframe rail from one side of the leadframe rail to the other.

15. (Original) The leadframe of claim 12 wherein the area of surface treatment on each of the leadframe rails comprises an area of the material coating each of the leadframe rails.

16. (Original) The leadframe of claim 15 wherein the material coating an area of each of the leadframe rails comprises a material that increases the adherence of the mold compound to the leadframe rails.

17. (Original) The leadframe of claim 15 wherein the material coating an area of each of the leadframe rails comprises a material that decreases the adherence of the mold compound to the leadframe rails.

18. (Original) The leadframe of claim 17 wherein the material coating an area of each of the leadframe rails comprises a surface lubricant.

19. (Original) The leadframe of claim 1 wherein each of the mold compound adherence areas comprises an area of increased surface roughness formed on opposite sides of a respective one of the leadframe rails.

20. (Original) The leadframe of claim 1, further comprising:
a plurality of integrated circuit attachment panels; and
a plurality of leads extending from each of the integrated circuit attachment panels.

21. (Original) An injection mold for molding a package for an integrated circuit, the injection mold comprising:

a first mold section including a plurality of mold cavities;
a second mold section including a plurality of mold cavities corresponding in number to the number of cavities included in the first mold section and having a size and a shape corresponding to the size and shape of the mold cavities in the first mold section; and
a leadframe positioned between the first and second mold sections, the leadframe having a pair of leadframe rails extending along opposite sides of the leadframe, the leadframe

further including a respective mold compound adherence area formed on each of the leadframe rails, the mold compound adherence area having properties that cause a mold compound to adhere to the mold compound adherence area to a significantly different degree than portions of the leadframe outside the mold compound adherence area.

22. (Original) The injection mold of claim 21 wherein a respective injection inlet adjacent is formed adjacent each of the mold cavities in the second mold section, and a respective mold vent is formed adjacent each of the mold cavities in the second mold section on adjacent an edge of the mold cavity opposite the injection inlet for the mold cavity in the second mold section.

23. (Original) The injection mold of claim 21 wherein the mold compound adherence areas comprise areas having properties that cause the mold compound to adhere to the mold compound adherence area more securely than portions of the leadframe outside the mold compound adherence area.

24. (Original) The injection mold of claim 21 wherein the mold compound adherence areas comprise areas having properties that cause the mold compound to adhere to the mold compound adherence area less securely than portions of the leadframe outside the mold compound adherence area.

25. (Original) The injection mold of claim 21 wherein the mold compound adherence areas are formed on opposite surfaces of the respective leadframe rails.

26. (Original) The injection mold of claim 21 wherein each of the mold compound adherence areas comprises at least one aperture formed in a respective one of the leadframe rails.

27. (Original) The injection mold of claim 26 wherein each of the mold compound adherence areas comprises a plurality of apertures formed in a respective one of the leadframe rails.

28. (Original) The injection mold of claim 26 wherein each of the apertures comprises an aperture having an elongated shape.

29. (Original) The injection mold of claim 21 wherein each of the mold compound adherence areas comprises an area of surface treatment formed on a respective one of the leadframe rails.

30. (Original) The injection mold of claim 29 wherein each of the areas of surface treatment comprises an area of increased surface roughness formed on a respective one of the leadframe rails.

31. (Original) The injection mold of claim 30 wherein each of the areas of increased surface roughness comprises a mechanically formed area of roughness.

32. (Original) The injection mold of claim 30 wherein each of the areas of increased surface roughness comprises a chemically formed area of roughness.

33. (Original) The injection mold of claim 29 wherein the area of surface treatment comprises an area of a material on each of the leadframe rails that is different from a material used to form another portion of the leadframe.

34. (Original) The injection mold of claim 33 wherein the area of material on each of the leadframe rails comprises a panel of the material that is bonded to the leadframe rail.

35. (Original) The injection mold of claim 33 wherein the area of material on the each of leadframe rails comprises a panel of the material that extends through the respective leadframe rail from one side of the leadframe rail to the other.

36. (Original) The injection mold of claim 33 wherein the area of surface treatment on each of the leadframe rails comprises an area of the material coating each of the leadframe rails.

37. (Original) The injection mold of claim 36 wherein the material coating an area of each of the leadframe rails comprises a material that increases the adherence of the mold compound to the leadframe rails.

38. (Original) The injection mold of claim 36 wherein the material coating an area of each of the leadframe rails comprises a material that decreases the adherence of the mold compound to the leadframe rails.

39. (Original) The injection mold of claim 21 wherein each of the mold compound adherence areas comprises an area of increased surface roughness formed on opposite sides of a respective one of the leadframe rails.

40. (Original) The injection mold of claim 21, further comprising:
a plurality of integrated circuit attachment panels; and
a plurality of leads extending from each of the integrated circuit attachment panels.

41. (Original) An injection molding machine for molding integrated circuit packages, comprising:

a first mold section including a plurality of mold cavities;

a second mold section including a plurality of mold cavities corresponding in number to the number of cavities included in the first mold section and having a size and a shape corresponding to the size and shape of the mold cavities in the first mold section;

a material reservoir containing a supply of a mold compound that is to be injected into the mold cavities;

an injection mechanism in fluid communication with the material reservoir and the injection vents, the injection mechanism forcibly injecting the mold compound from the material reservoir into the mold cavities;

a heating mechanism for heating the mold sections; and

a leadframe positioned between the first and second mold sections, the leadframe having a pair of leadframe rails extending along opposite sides of the leadframe, the leadframe further including a respective mold compound adherence area formed on each of the leadframe

rails, the mold compound adherence area having properties that cause a mold compound to adhere to the mold compound adherence area to a significantly different degree than portions of the leadframe outside the mold compound adherence area.

42. (Original) The injection molding machine of claim 41 wherein a respective injection inlet adjacent is formed adjacent each of the mold cavities in the second mold section, and a respective mold vent is formed adjacent each of the mold cavities in the second mold section on adjacent an edge of the mold cavity opposite the injection inlet for the mold cavity in the second mold section.

43. (Original) The injection molding machine of claim 41 wherein the mold compound adherence areas comprise areas having properties that cause the mold compound to adhere to the mold compound adherence area more securely than portions of the leadframe outside the mold compound adherence area.

44. (Original) The injection molding machine of claim 41 wherein the mold compound adherence areas comprise areas having properties that cause the mold compound to adhere to the mold compound adherence area less securely than portions of the leadframe outside the mold compound adherence area.

45. (Original) The injection molding machine of claim 41 wherein the mold compound adherence areas are formed on opposite surfaces of the respective leadframe rails.

46. (Original) The injection molding machine of claim 41 wherein each of the mold compound adherence areas comprises at least one aperture formed in a respective one of the leadframe rails.

47. (Original) The injection molding machine of claim 46 wherein each of the mold compound adherence areas comprises a plurality of apertures formed in a respective one of the leadframe rails.

48. (Original) The injection molding machine of claim 46 wherein each of the apertures comprises an aperture having an elongated shape.

49. (Original) The injection molding machine of claim 41 wherein each of the mold compound adherence areas comprises an area of surface treatment formed on a respective one of the leadframe rails.

50. (Original) The injection molding machine of claim 49 wherein each of the areas of surface treatment comprises an area of increased surface roughness formed on a respective one of the leadframe rails.

51. (Original) The injection molding machine of claim 50 wherein each of the areas of increased surface roughness comprises a mechanically formed area of roughness.

52. (Original) The injection molding machine of claim 50 wherein each of the areas of increased surface roughness comprises a chemically formed area of roughness.

53. (Original) The injection molding machine of claim 49 wherein the area of surface treatment comprises an area of a material on each of the leadframe rails that is different from a material used to form another portion of the leadframe.

54. (Original) The injection molding machine of claim 53 wherein the area of material on each of the leadframe rails comprises a panel of the material that is bonded to the leadframe rail.

55. (Original) The injection molding machine of claim 53 wherein the area of material on the each of leadframe rails comprises a panel of the material that extends through the respective leadframe rail from one side of the leadframe rail to the other.

56. (Original) The injection molding machine of claim 53 wherein the area of surface treatment on each of the leadframe rails comprises an area of the material coating each of the leadframe rails.

57. (Original) The injection molding machine of claim 56 wherein the material coating an area of each of the leadframe rails comprises a material that increases the adherence of the mold compound to the leadframe rails.

58. (Original) The injection molding machine of claim 56 wherein the material coating an area of each of the leadframe rails comprises a material that decreases the adherence of the mold compound to the leadframe rails.

59. (Original) The injection molding machine of claim 41 wherein each of the mold compound adherence areas comprises an area of increased surface roughness formed on opposite sides of a respective one of the leadframe rails.

60. (Original) The injection molding machine of claim 41, further comprising:

a plurality of integrated circuit attachment panels; and

a plurality of leads extending from each of the integrated circuit attachment panels.

61-100. (Canceled)